



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2814
Examiner: Phat X. Cao

In re PATENT APPLICATION of:

Applicant(s): Nobuhisa KUMAMOTO et al.)
Serial No.: 10/767,439)
Filing date: January 30, 2004) PETITION FOR
For: PROCESS OF PRODUCING)
SEMICONDUCTOR CHIP WITH)
SURFACE INTERCONNECTION)
AT BUMP (as amended))
Atty. ref.: AI 318 D1)

August 22, 2006

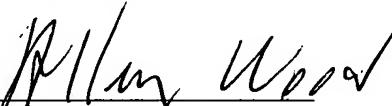
Director of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please extend the period for responding to the Office Action of March 22, 2006 by two months, and thus until August 22, 2006.

A remittance that includes the \$450 extension fee is being submitted concurrently. Should this remittance be accidentally missing or insufficient, though, any fees that may be needed can be charged to our Deposit Account number 18-0002.

Respectfully submitted,


Allen Wood

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450.00 0P

AW/ng

FEE ENCLOSED: \$ 450.00
Please charge any further
fee to our Deposit Account
No. 18-0002